



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Hall et al.

**Serial No.:** 10/785,122

**Filed:** February 24, 2004

**For:** UNDERFILLED, ENCAPSULATED  
SEMICONDUCTOR DIE ASSEMBLIES  
AND METHODS OF FABRICATION

**Confirmation No.:** 1653

**Examiner:** J. Diaz

**Group Art Unit:** 2815

**Attorney Docket No.:** 2269-5165.1US  
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**Notice of Allowance Mailed:**

May 4, 2006

**NOTICE OF EXPRESS MAILING**

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Person making Deposit: Wendy Neff

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 2 of this paper;

**Amendments to the Abstract** appear on page 4 of this paper; and

**Remarks** start at page 5 of this paper.